

IN THE ABSTRACT - (CLEAN COPY)

Please delete the Abstract section without prejudice, and replace it with the following.

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ABSTRACT

A method for producing a package (30) for a semiconductor die (or chip) including a semiconductor die (20) having one or more bond pads on the top surface for providing terminals for one or more sensors (22) in the upper surface and a die carrier (32) including an opening (34) and one or more external terminals. The semiconductor die (20) upper surface is fixed to the die carrier (32) and each bond pad is coupled to a portion of the external terminals exposed at the die carrier (32) lower surface, for example, with weld points (42). A sealing ring (44,46) encapsulates the interface zone (40) and a coating material (48) encapsulates the die carrier (32) lower surface and a lower surface of the semiconductor die (20).

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IN THE CLAIMS - (CLEAN COPY)

✓ Please cancel claims 1-19 without prejudice.

Please add new Claims 20-46, as follows.

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